Z21 Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

Z22 These assemblies are ESD sensitive, ESD precautions shall be observed.

Z23 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z24 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: 001

<table>
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<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: TIDA-01586</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
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<td>GENERATED : 2/2/2018 1:05:13 PM</td>
<td>TEXAS INSTRUMENTS</td>
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**Components marked 'DNP' should not be populated.**

**Assembly Variant: 001**

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<th>PCB Viewed from Bottom Side</th>
<th>Board #: TIDA-01586</th>
<th>Rev: E1</th>
<th>SVN Rev: Not in VersionControl</th>
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